

Micro-mouse Project Brief

EEE3088F 2025



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0 General Instructions

This document contains the project description as well as all documentation on the micro-mouse (MM). Please read this document carefully and make sure that you understand all the project requirements. There are four assessments linked to the project:

1. The *Gerber Files* submission (Friday, 28 March 2025 at 5pm on Amathuba)
2. The *Interim Design Report* (Friday, 25 April 2025 at 5pm on Amathuba AND Gradescope)
3. The *Lab demonstration* (can be conducted every lab session until the final due date on Wednesday, 14 May in White Lab)
4. The *Final Report* (Friday, 16 May 2025 at 5pm on Amathuba AND Gradescope)

A special note is that the report assessments are **individual**. You are each expected to submit individual reports as per the assignment descriptions (later in this document).

Group work

For the remainder of the semester, you will continue to work in your chosen pairs from the breadboard assignment.

In your pairs, you will work together on a **single** PCB solution and will **both** be required to attend the lab **demonstrations**. The demonstration will be a **group mark**. However, **you will each be required to submit individual reports and will receive individual report marks**. In these reports, you will write the design and other sections based on the parts of the system you chose to design (more on this later).

As always, we encourage you to communicate and collaborate with your teammate throughout the course, it will take you farther than if you go alone.

General notes

1. Effective communication is a core engineering skill. Asking the right questions and engaging with clients ensures that you will deliver the correct product. If something isn't clear, research it. If you're still unsure, ask—suffering in silence leads to mistakes and lost time.
2. This is a live document, make sure to regularly check for updates and to download the latest versions so that you do not miss out on key changes (these will also be noted in the Errata section).
3. During lab sessions, tutors will be available to help you. However, to make the most of this time, you will need to do additional work outside of these hours.
4. **All reports must be written in LaTeX.**
5. **You will need to use GitHub for version control and be required to upload the link in your reports.**

1 Project Overview

The course project involves building some subassemblies for your very own (simplified) micro-mouse.

What is a Micro-Mouse?

In short, it is a maze-solving robot. Watching the [Veritasium video](#) will give you a clearer understanding of what a micro-mouse is, however it is important to note that your micro-mouse will likely (almost certainly) be much slower than the ones featured in the video. Nonetheless, let the video serve as inspiration for your project.

What is your project?

In this course you will be focusing on the design of the micro-mouse's hardware (with the possibility of some minor software components). The complexity of this project is in meeting the requirements while still adhering to the STRICT budget.

The micro-mouse has been compartmentalised into four modules: the processor, motherboard, sensing and power. The processor, motherboard and sensing modules have been designed and will be given to you. **Your project involves designing and manufacturing the power module.** More information about each module is provided in the table below.

Module	Description
The motherboard	The motherboard has already been designed is responsible for connecting all the PCBs together. It is the base board that all other modules will slot onto.
The processor	The processor board has already been designed. It has an STM32L476 microcontroller onboard, a significant upgrade in performance compared to the 2 nd year STM32F051. It is a 100-pin package and has 78 output pins that are available to use. Most of these have already been dictated by the required interconnections between the micro-mouse's supplementary modules.
The sensor	This module has already been designed and will be responsible for detecting/sensing objects.
The power	This module will be responsible for powering the entire system. You will need to design and manufacture this module to fit the requirements detailed in this document.

To be successful, you will need to understand how your component fits into the greater picture and what you would need to do to meet the requirements.

2 Project Background

This section contains information about the entire MM. It is important to take note of all subsystems and their requirements when working on the project.

The Motherboard

Interfaces	Description
Processor board	Two sets of 2x19 (2.54mm pin pitch) pin sockets (<i>pinouts listed in the processor section</i>).
Motors	Two sets of 2x1 (2.54mm pin pitch) pin headers.
Sensor board	2x16 (2.54mm pin pitch) pin sockets (<i>pinouts listed in the sensor section</i>).
Power board	2x16 (2.54mm pin pitch) pin sockets (<i>pinouts listed in the power section</i>).

Table 1 Motherboard interfacing connections

The image below features a pin view of the Motherboard PCB. This is the exact layout and shape of the motherboard. You must design your power PCBs to fit onto the specified power connection. *Take special note the position of the center of rotation of the robot. The center of rotation is under the IMU.*

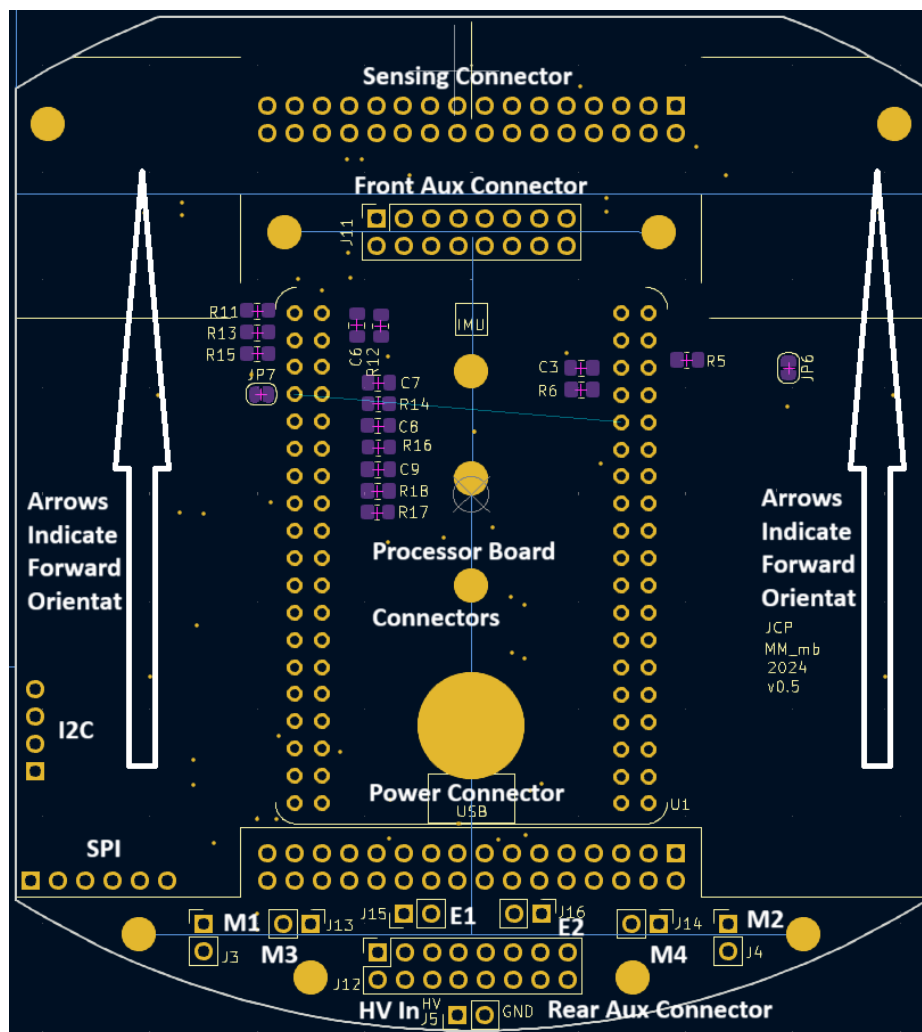


Figure 1 Pin-view of the MM Motherboard PCB.

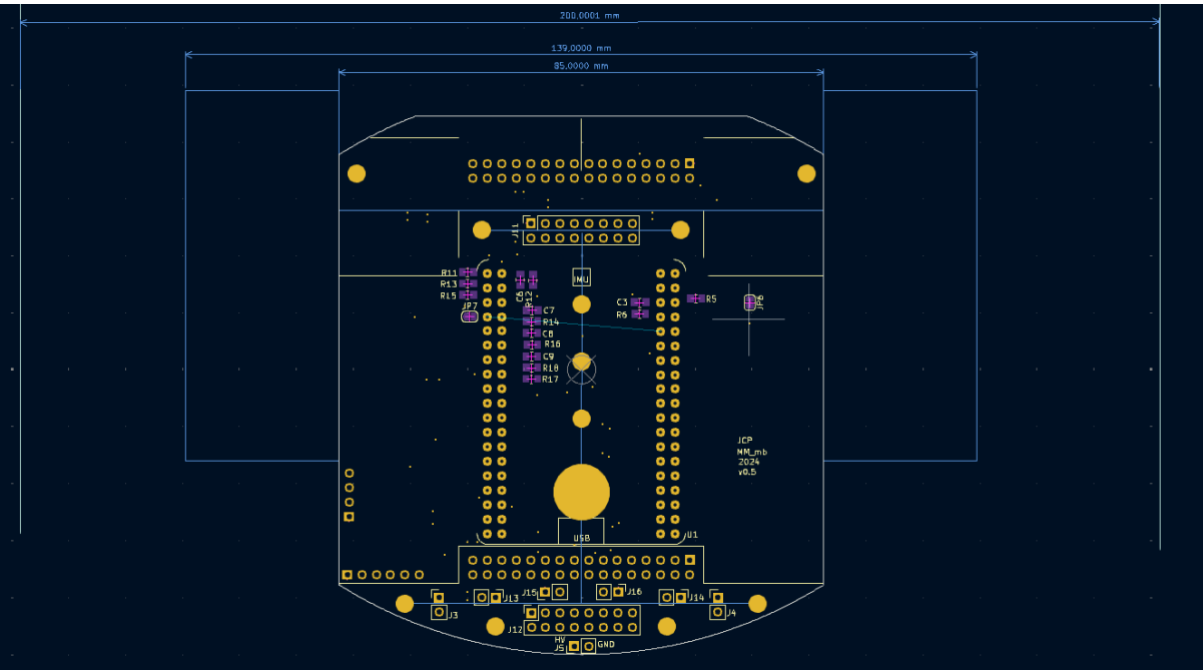


Figure 2 Dimensions of MM

The Processor

The processor board with the STM32L476 microcontroller on it. The images below depict the 3D PCB render and the schematic of the **processor board**.

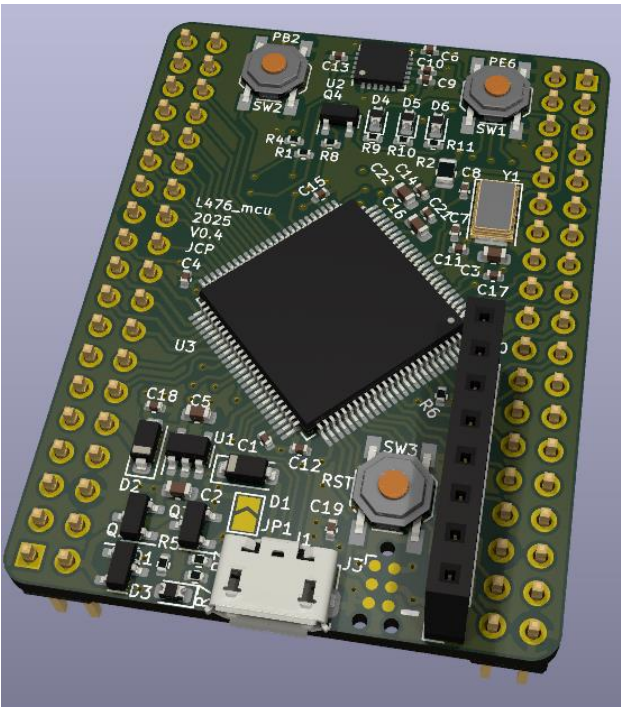


Figure 3 3D Render of the MM Processor PCB

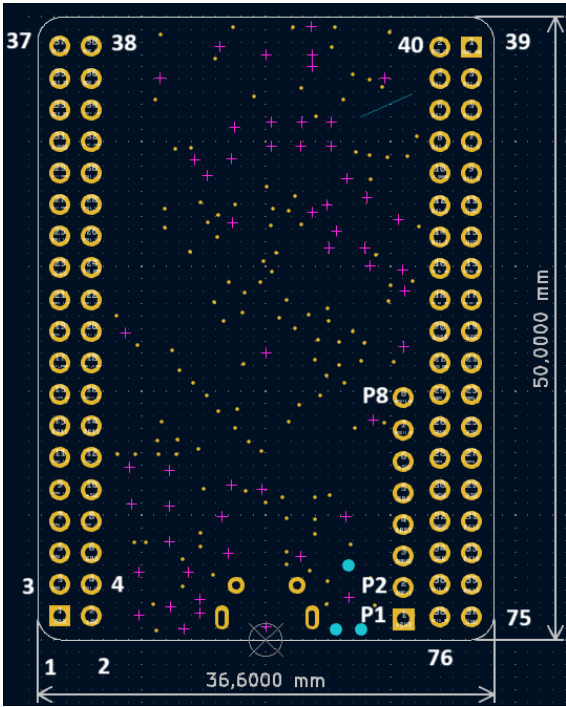


Figure 4 Pin-view of the MM Processor PCB

The following table highlights the pinouts of the processor board:

Pin Number	Associated to	Useful/Function
1	PA8	
2	VBAT	

3	PC9	
4	PC8	
5	PC7	

6	GND	
7	PC6	
8	PD15	
9	PD14	
10	5V	
11	PD13	
12	PD12	
13	PD11	
14	PD10	
15	PD9	
16	PD8	
17	PB15	
18	PB14	
19	PB13	
20	PB12	
21	PB11	
22	PB10	
23	GND	
24	PE15	
25	PE14	
26	PE13	
27	PE12	
28	PE11	
29	PE10	
30	PE9	
31	3V3	TLV740P
32	PE8	
33	PB1	
34	PE7	
35	PB0	
36	PC5	
37	PC4	
38	PA7	
39	PA5	
40	PA6	
41	PA3	
42	PA4	
43	PA1	
44	PA2	
45	PC3	
46	PA0	
47	PC2	

48	3V3_ADC	
49	GND	
50	PC1	
51	PE1	
52	PC0	
53	PE4	
54	PE5	
55	PE2	
56	PE3	
57	PE0	
58	NRST	
59	PB8	
60	PB9	
61	PB7	
62	PB6	
63	PD7	
64	PB4	
65	PD5	
66	PD6	
67	PD3	
68	PD4	
69	PC11	
70	PD2	
71	PC10	
72	GND	
73	PA15	
74	PD1	
75	GND	
76	PD0	
USB Micro Connector	Standard USB Connector	
Prog_3V3 (P1)	Target Voltage sense	
Prog_SWCLK (P2)	SWCLK	
Prog_SWDIO (P3)	SWDIO	
Prog_NRST (P4)	NRST	
Prog_GND (P5)	GND	
Prog_5V (P6)	Programming Power	
Prog_VCP_In (P7)	USART1_Tx	
Prog_VCP_Out (P8)	USART1_Rx	

Table 2 Electrical pinout of the MM Processor PCB

Sensing System

The sensor module is effectively the “eyes” of the MM and provides information to the processor to determine whether there is an obstruction in the way of the MM.

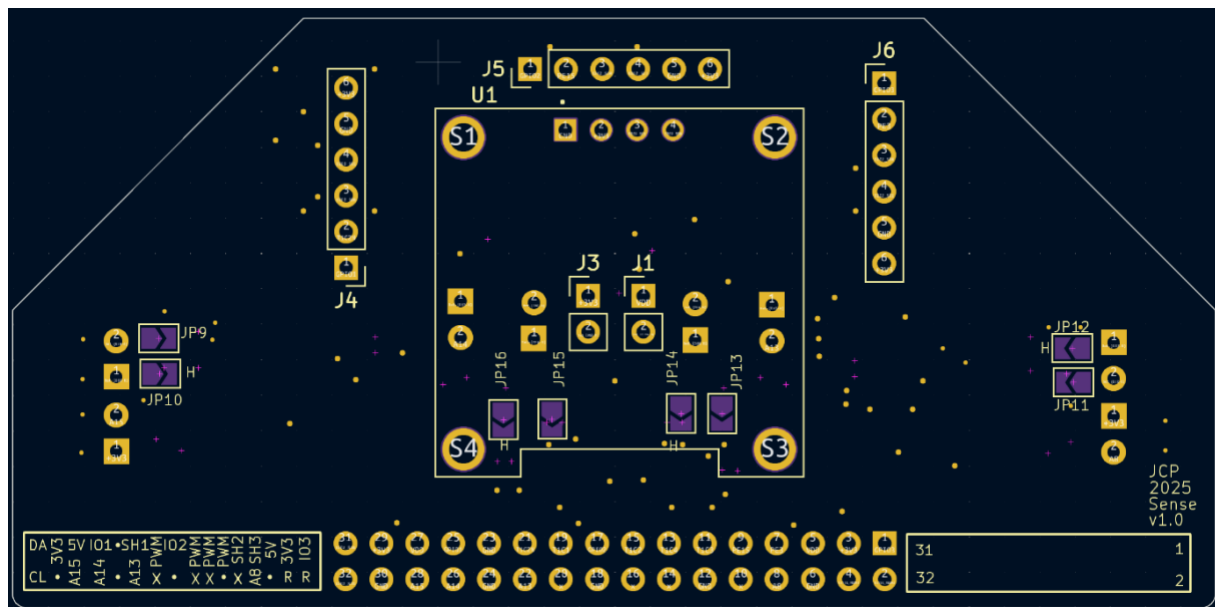


Figure 5 MM Sensing pinouts that plug in the MM Motherboard PCB

Pin Number	Associated to	Useful
1	GPIO3	PE2
2	RESV	PE1
3	3V3	
4	RESV	PC2
5	5V	
6	GND	
7	XSHUT3	PE3
8	A8	PA3
9	XSHUT2	PE15
10	NC	
11	T1C3	PE13
12	GND	
13	T1C4	PE14
14	NC	
15	T1C2	PE11
16	NC	
17	GPIO2	PE12
18	GND	
19	T1C1	PE9
20	NC	
21	XSHUT1	PE10
22	A13	PC4
23	GND	GND

24	GND	PB11
25	GPIO1	PE8
26	A14	PC5
27	5V	
28	A15	PB0
29	3V3	
30	GND	GND
31	SDA	PB11
32	SCL	PB10

Table 3 Electrical pinout of the Sensor PCB

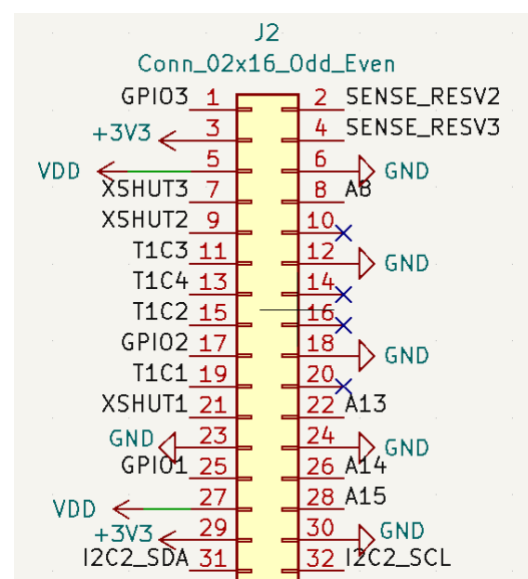


Figure 6 Sensor PCB Connector and pin layout

Micro-sensing Board

The primary improvement between sensing boards in 2024 and 2025 is that the previous only had proximity sensors which provided information on whether there was a wall next to the robot. In 2025, there are 3 distance sensors for left/right and forward sensing. This should provide significantly more information for the MM.

To achieve this, STM Time of Flight sensors (ToF) were implemented. The sensors operate on I2C and were built onto a smaller daughter board called the MicroSensing board (for now).

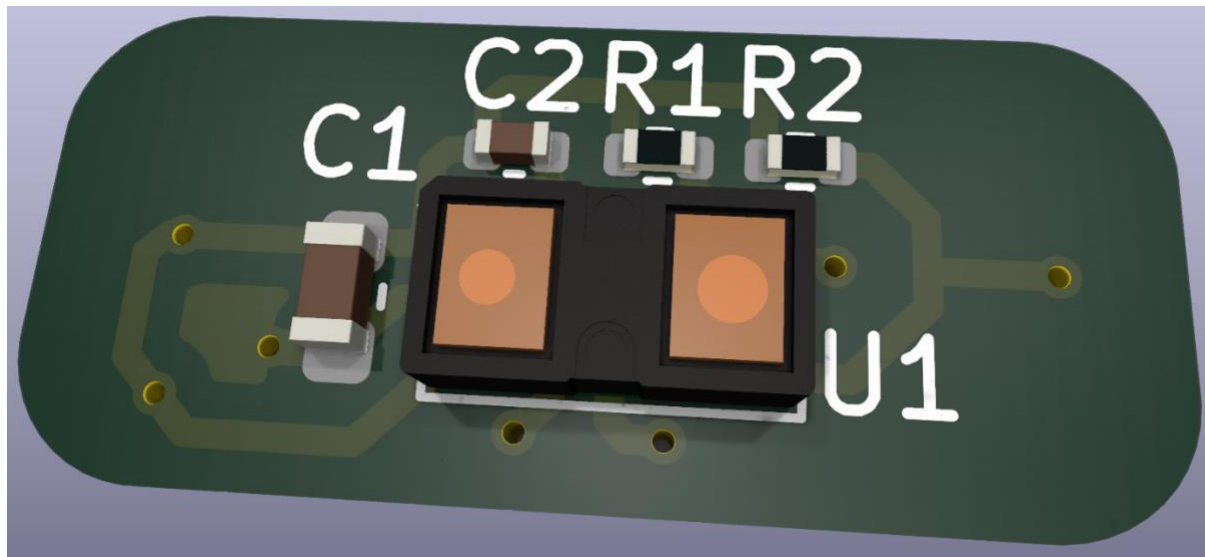


Figure 7 MM micro-sensing daughter board PCB

The Maze

The MM will ultimately need to navigate through a maze (this will be the second semester design goal). The maze will have dead ends and **multiple paths to the finishing area** with each pixel being a 200mm square. An example is provided below:

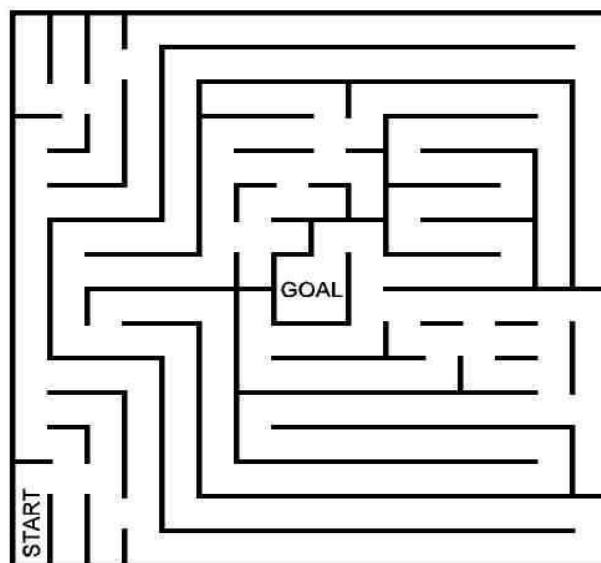


Figure 8 Example of a MM maze.

Power System

In the first semester, you will be working in your groups to design and manufacture this subsystem.

Battery

The battery will be: [Battery LiPo 800mAh 3.7V - Micro Robotics](#).

Typically, try keep the max discharge at 0.5C (Capacity) for this type of battery. This implies 400mA max draw and from full to fully discharged in 2 hours. The better you control the charging and discharging conditions the better the overall battery operational lifetime. This isn't a requirement for our project, but something worth noting.

3 Project Description

Overview

As with the breadboard assignment, you will continue to work in your groups. To be clear, you will work together on designing a single PCB to fulfill the **power module** requirements.

Although you are working in a group, you will each be required to take responsibility for certain parts of the power module's design. The **demonstration will be assessed as a group** whilst both the Interim and Final Design Reports are **individual assessments**. In the design sections of the reports you will focus in on writing about the parts of the solution that you designed.

Power Subsystem Requirements

For the course project your group is required to design the power subsystem for the MM. To achieve this, your module will need to:

- Operate up to 4 motors bidirectionally with the pins available to you (*listed in the power pinout table*). You will need to control 2x **brushed DC** motors which could each draw 200mA at the highest voltage of a 1S1P battery (the battery is further specified in the [battery section](#)). The other 2x motors are for the auxiliary connection and need to operate 500mA each.
- Place an INA219 **for monitoring the battery** on the I2C Bus and configure it correctly with respect to the hardware (**cannot have BOTH A0 AND A1 on GND**)
- Charge the battery from the 9V input pin (*listed in the power pinout table*).
- Have two charging modes for a higher and lower charging current for the battery (200mA, and approximately 600mA ± 100 mA **from the battery perspective**).
- Integrate USB C and get 9V out of the USB Host
- Provide 2x External Load Switching at 1A each (**High Side connected to your 5V**)
- Provide a 3V3 **5% accuracy (300mA max)** and 5V Out **5% accuracy (1.5A max)**
- Provide an ON/OFF switch. **OFF state: battery draw <30uA. ON state: can provide your robot peak current of 2A.** The switch needs to shut down 5V and 3V3.

Spend a little time looking through these requirements, ranking them in difficulty and share the tasks evenly between you and your colleague. You will write about your chosen parts your individual report.

Additionally, the following connectors need to be included:

1. **A JST PH 2mm pin pitch** connector for the battery. The battery will be tucked away between the motherboard PCB and the processor PCB.
2. **A 2x16 (2.54mm pin pitch) pin header:** It needs to fit onto the MM's motherboard 2x16 2.54mm pitch connector with the correct pinout. **Hint: be sure to pay attention to the alignment of the pins**
3. The maximum dimensions for your board are 82 x 60 for it to fit under the motherboard PCB. Please note this even though JLC allows larger.
4. The shape of the board is an important consideration: If your board extends to any of the drill holes on the MB, your power

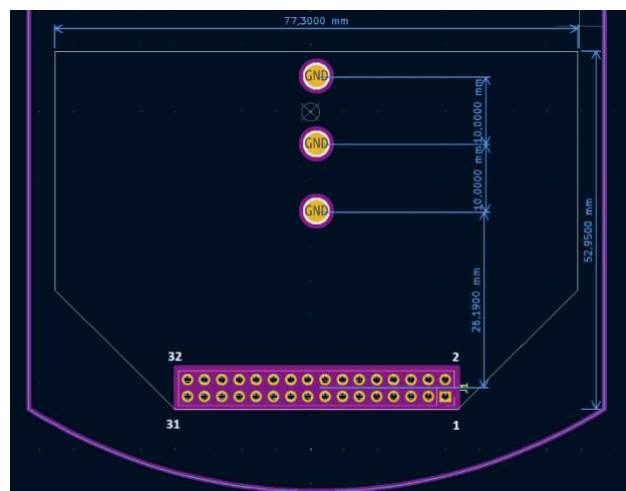


Figure 9 MM Power PCB pinouts that plug onto the MM Motherboard PCB (Example shape).

board needs to use them for securing your PCB as the weight of the PCB will be too much for the connector alone.

5. The Motherboard dimensions arc radius is 80mm and the connectors centre is 15.3mm from the apex of the arc.

The table below surmises the connections for the board

Connector	Pin Number	Associated to	Useful Info
	1		Motor2_B_OUT
	2		Motor2_A_OUT
	3		Motor4_A_OUT
	4	PD12/ TIM4C1	MOTOR2_CTRL1
	5		Motor4_B_OUT
	6	PD13/ TIM4C2	MOTOR2_CTRL2
	7	PD2	CTRL_EXT_LOAD2
	8	PD14/ TIM4C3	MOTOR4_CTRL1
	9	PD6/RESV	USART2_RX
	10	PD15/ TIM4C4	MOTOR4_CTRL2
	11		EXT_LOAD2_OUT
	12	PD5/RESV	USART2_TX
	13	PB4	FAST_CHARGE_CTRL
	14		Battery
	15	PD7/ RESV	
	16	PB8	I2C1_SCL
	17	PB9	I2C1_SDA
	18		3V3 Out
	19		GND

2x16 pin (2.54mm pin pitch) header	20		5V Out
	21		EXT_LOAD1_OUT
	22	HV	HV
	23		GND
	24	PC6/ TIM3C1	MOTOR3_CTRL1
	25	PD11	CTRL_EXT_LOAD1
	26	PC7/ TIM3C2	MOTOR3_CTRL2
	27		MOTOR3_A_OUT
	28	PC8/ TIM3C3	MOTOR1_CTRL1
	29		MOTOR3_B_OUT
	30	PC9/ TIM3C4	MOTOR1_CTRL2
	31		MOTOR1_B_OUT
	32		MOTOR1_A_OUT
Battery Connection	JST PH 2mm pin pitch	Your board	
USB Connection	Type C	Your board	

Table 4 Electrical pinout of the MM Power PCB

Budget

Before we break this down, please note that when ordering the PCBs you will ONLY NEED TO POPULATE the USB-C connectors. To be clear, **we will provide you with the pin headers and JST connectors** described in the power subsystem section. You will still need to provide the footprint on your PCB but will not populate them in your BOM.

Now to truly understand the difficulty of each task, you each have a total of \$35 to have your board manufactured. That is 5x PCBs made @ \$4, 2x PCBs populated @ \$9.50 and then your component costs.

\$13.5 is being used to manufacture a standard sized simple board. So, you have $35 \times 2 = \$70$ worth of components on the sum of your board section. \$56.5 on components. Pay attention to extended parts...

Just explaining it one more time:

Item	Student 1	Student 2
Starting Allowance	\$35	\$35
PCB Manufacture (5 units)	\$4	
PCB Assembly (2 units)	\$9.50	
Remaining Budget for components	\$56.5	
OR alternatively	Approx. \$28.25 for components for your section	Approx. \$28.25 for components for your section
NOTE:	If your board is ANYTHING over \$70, it cannot be ordered.	

Table 5 Budget Explanation per Student

If for some reason your board fails to meet the basic requirements or is too expensive, it will not be able to be ordered

General Notes

1. For this project, your design challenge is to meet the budget requirements WITHOUT the use of additional resources. Using components from the bread board assignment or elsewhere is NOT permissible in this project.
2. The extended component fee is paid PER board order but not per individual PCB of that order. For example, I am designing the PCB and require an extended component which costs R1 but has an extended fee of R10. When I place my order, I will be populating 2 boards with this component BUT I will only pay the extended fee **once**. This means that to populate both boards with this component I will only pay $2 \times R1 + R10 = R12$ NOT $2 \times (R1 + R10) = R22$.
3. Do not choose to not populate resistors and components with the expectation that you will receive them from White Lab. White Lab components will be give out on a case-by-case basis – but you certainly **will not receive WL components if you did not populate them in your order**.
4. When ordering the PCBs DO NOT POPULATE the 2x16 connector nor the battery connector. To be clear, we will provide you with the pin headers and JST connectors described in the sensing and power subsystem sections. You will still need to provide the footprint on your PCB but will not populate them in your BOM.

What is expected

1. In your pairs, you are required to evenly divide up the 8 tasks/requirements. Take some time to understand each task and rank them amongst yourselves based on difficulty. Note that these are the tasks that you will discuss in the design sections of your Interim Design Report.
2. You will need to submit
 - a. Production files (Gerber, BOM and PnP files for a single PCB) in your pairs by the due date.
 - b. an Interim Design Report in which you will document all the design decisions that you have made and your solution to the problem.
 - c. Demonstrate your board
 - d. A Final Design Report
3. You will need to check this document frequently and redownload it when more information becomes available.

4a Project Assignment: PCB Production Files

Instructions

You will need to submit all the production files for your PCB on [Amathuba](#) by the **28th of March 2025 at 5pm**. Late submissions will not be accepted as the boards will not arrive on time for you to complete the course.

You need to submit a single zipped folder with the following naming convention: **EEE3088F 2025 Project PCB Files Group xx STUDENTNUMBER1 STUDENTNUMBER2.zip** e.g. EEE3088F Project PCB Files Group 10 FRRTRI001 XYZMNO009.zip. The zipped folder must contain:

1. A zipped file containing your Gerbers. **Please write your student numbers and group number on the silkscreen of your PCB**
2. The Bill of Materials (BOM) .csv file
3. The POS/CPL .csv file
4. A screenshot of JLCPCB BOM page after you have successfully uploaded all your files.
5. A screenshot of the JLCPCB add to cart page after you have successfully uploaded your files. With the naming convention

More Information

Use JLCPCB tools to generate the production files and then provide:

1. A zipped file containing your Gerbers
2. The Bill of Materials (BOM) .csv file
3. The POS/CPL .csv file

Before submitting, you need to upload these files to JLCPCB as if you were going to order the boards. During this activity, you will need to take a screenshot of the:

4. BOM page
5. JLC add to cart page.

These screenshots will also need to be uploaded to Amathuba with the following naming conventions:

- **EEE3088F_Project_JLCPCBBOM_studentnumber**
- **EEE3088F_Project_JLCPCBacceptance_studentnumber**

These screenshots will serve as proof of your ability to submit the files as if you were going to place the order on JLCPCB yourself.

Notes

1. Please write your student numbers and group number on the silkscreen of your PCB
2. The JLCPCB tool generates these files for you. If your board is not JLCPCB compliant (you do not provide the files generated by JLCPCB tools) your board will not be ordered.
3. Please make sure to choose components that are well stocked – if your components are not in stock when we order then your PCB will return incomplete.
4. Do not choose to not populate resistors and components with the expectation that you will receive them from White Lab. White Lab components will be give out on a case-by-case basis – **you will not receive WL components if you did not populate them in your order.**

4b Project Assignment: Interim Design Report

Using the [NEW LaTeX report](#) template available on Amathuba, you are required to write a report about the subsystem you have designed.

Notes:

- This report is an individual submission.
- Feel free to add in subsection headings when writing the report, but do not make changes to the chapter names and section names in the template. When uploading to Gradescope, the rubric will expect you to have the section names described below. This is important for the markers.
- Marks will be allocated to report presentation (grammar, formatting, use of space, etc.).
General presentation remarks:
 - ***Do not write in first person i.e. using I, we, us, they, them, him, her, etc.***
 - Include a title page, the plagiarism declaration and table of contents. If you have citations, include a Bibliography (remove this where it is not used).
 - Ensure that table headings are above the table and that figure headings are below the figure (IEEE standard).
- You will be penalised for not assigning pages on Gradescope.
- You will be penalised for exceeding the page limit. **The 12-page page limit includes the pages used to add in figures and tables.** The limit does not include the cover page, plagiarism declaration, table of contents or the bibliography.
- **You will be penalised for overlapping discussions with your group member in certain sections. Pay attention to the expectations of the report.**

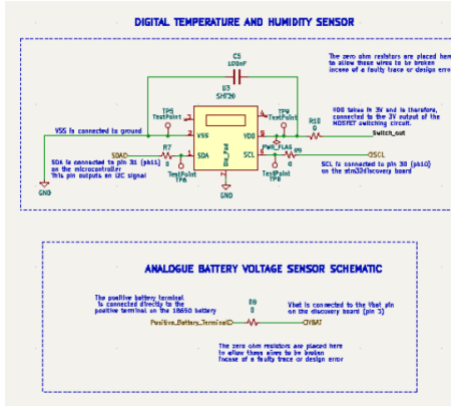
Report Expectations

You are expected to write this report individually. In some of the sections you are specifically required to highlight what work you have done on the design of the solution. Please pay special attention to where these sections are.

The table below highlights the expectations for the Interim Design Report

Report structure		Description	Notes	Page limit
Chapter	Section			
Introduction	Problem Description	Holistically summarise the project problem: <ul style="list-style-type: none"> - What is the context? - What is the greater project? - What is your specific problem in the context of the greater problem? 	Written about overall power subsystem.	1
	Scope and limitations	<ul style="list-style-type: none"> - Highlight exactly what your project entails and what it does not entail. - Highlight what limits the project designs, testing, development, etc. 	Written about overall power subsystem.	
	GitHub Link	Provide the link to your group's shared repository. The files should be organised logically and there should be a repo README. <i>Please make sure that the link is correct, and that the repository is publicly visible at the time of submission.</i>	Written about overall power subsystem.	
Requirements Analysis	Traceability Analysis	<ul style="list-style-type: none"> - Create your own version / complete the table in the template to show how the requirements, specifications and testing procedures all link. Use the IDs to show this. You are only expected to fill in the ATP column for the 5 ATPs that you have completed in your report but must still show all requirements and specifications. - Write a description for each completed row in the matrix (the rows where you have assigned an ATP): <ul style="list-style-type: none"> o Briefly describe/motivate/highlight how everything links and why. These descriptions should clearly convey your thought process behind the specifications and testing procedures you have come up with. <i>You may present this information however you see fit – it must be clear and easy to follow.</i> o The idea here is to see your critical thinking about why and how you derived the specifications and tests in this section. 	Each group member should cover different parts of the design. No overlapping tests will be accepted.	5
	Requirements	Fill the template /create a requirements table, give it a meaningful heading. Make sure to give each requirement a unique ID.	Written about overall power subsystem.	

	Specifications	Fill the template /create a specifications table, give it a meaningful heading. Make sure to give each specification a unique ID.	Written about overall power subsystem.	
	Acceptance Testing Procedures	<p>Give 5 tests that you will conduct on your board to verify that your system meets some of the requirements and specifications. 5 tests are not comprehensive enough to test for all reqs and specs, rather you are tasked to show thinking around testing some parts of your system. To do this, create your own version / complete the table in the template:</p> <ul style="list-style-type: none"> - Provide each test with a unique ID - What is the test? Why is it being tested? - Concisely explain how you will test (using jumpers, test points, what equipment, etc.). Explain the procedure. - What is the pass/fail criteria be specific, general statements such as “turns on” are incorrect. <p>Notes:</p> <ol style="list-style-type: none"> 1. Please note that each requirement and specification could have more than one ATP associated with it BUT one ATP CANNOT be associated with multiple specifications or requirements. 2. This is specifically with regards to HOW you will test your PCB to verify that every part of it works as expected. This is different to the Failure management section in that you are not describing measures you took to prevent failure on the board. Rather, imagine that you now have the board, describe how you will prove that you met the requirements and specifications. 	Each group member should cover different parts of the design. No overlapping tests will be accepted.	
Subsystem Design	Design Decisions	<p>Discuss 3 unique design decisions you have made:</p> <ul style="list-style-type: none"> - To ensure that your report flows, these need to link back to the specifications and requirements that you chose ATPs for. - Comparison of passive component values alone will not be considered as design decisions. - For each design decision: <ul style="list-style-type: none"> o Briefly make it clear why this decision is necessary (i.e. link to the reqs/specs) 	Each group member should cover different parts of the design. No overlapping design decisions will be accepted. These decisions should link to the ATPs you have previously described.	5

		<ul style="list-style-type: none"> ○ Evidence of options considered as well as thoughtful and relevant comparisons (using tables, diagrams, calculations, etc.) ○ Clearly state the final decision and why. It is good practice to link back to the specifications/requirements. 		
	Final Design Description Summary	<ol style="list-style-type: none"> 1. Write a summary of your final design: <ul style="list-style-type: none"> - Describe your solution - Since you are only required to discuss 3 unique design decisions, you will only need to cover how these link back to solving the overarching problem. - Do not be verbose, it is only a summary. 2. Provide a screenshot of your final schematic (this should only include the requirements and specifications that you designed solutions for). Make sure to: <ul style="list-style-type: none"> - Include the title block with version number, author name, date, schematic title. - Include comments explaining what different parts of the schematic are for and do. - Neaten up the schematic so that it is easy to follow. - All labels used should be clear and describe the connection well e.g. PA7_VADC 3. Provide screenshots of your group's PCB (front and back and then one 3D viewer screenshot). 		Each group member should cover different parts of the design. No overlapping will be accepted.
	Failure Management	<ul style="list-style-type: none"> - List/Tabulate at least 3 plausible and sensible failure management processes taken and why (concisely) 	Each group member should cover only the parts they	

		<ul style="list-style-type: none"> - Make sure that you give each a clear descriptive name that describes what it is. <p><i>This is specifically with regards to post-design phase (how you add measures to fix something on your PCB when it has arrived). These are pre-emptive steps you have taken to ensure that if something in your circuitry is broken/incorrectly connected/etc, you are still able to fix it once the board arrives. This is where you discuss how you designed the PCB to mitigate component failures/trace issues/errors in your circuit design/etc.</i></p>	applied to their section of the design. No overlapping will be accepted.	
	System Integration and Interfacing	<ul style="list-style-type: none"> - Replace the <i>template table</i> with your own table that clearly shows which pins connect to and interact with other parts of the system (specifically the motherboard interface). This needs to be much more than the tables we have given you in this project brief. - Include a simple, high level (do not draw a circuit diagram or go into detail) interfacing diagram showing how your subsystem fits into the larger micro-mouse system. This should include information about expected inputs/outputs and/or what the interactions are and/or pin connections. <p><i>The table and diagram should describe and display the same information. The idea here is to show you two different ways in which interfacing information can be conveyed.</i></p>	Written about overall power subsystem.	
Results and Discussion		This will only be completed for the final report.		0
Recommendations		This will only be completed for the final report.		0
Extra page for formatting.				1

4c Project Assignment: Final Demonstration

Coming soon...

4d Project Assignment: Final Report

Coming soon...

5 Appendix: Errata

Most recent changes are in Orange.

Version 2 –

- Modified the Requirements for the PCB to be more specific.
- Highlighted more mechanical information on the PCB connection to the motherboard on note 5.
- Modified the pinout table to be more specific on which pins are responsible for functioning on the Power board.

Version 3

- Added in Interim Design Report expectations.